

NCE Automotive N-Channel Enhancement Mode Power MOSFET (Primary)

Description

The NCEA0130AG uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. It can be used in a wide variety of applications.

Application

- Automotive application
- Power switching application
- Hard switched and high frequency circuits
- Uninterruptible power supply

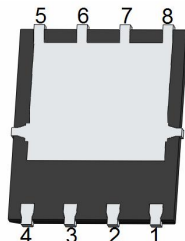
General Features

- $V_{DS} = 100V, I_D = 36A$
- $R_{DS(ON)} < 32m\Omega @ V_{GS}=10V$ (Typ:24m Ω)
- $R_{DS(ON)} < 35m\Omega @ V_{GS}=4.5V$ (Typ:27m Ω)
- High density cell design for ultra low R_{dson}
- Good stability and uniformity with high E_{AS}
- Excellent package for good heat dissipation
- 175 °C operating temperature
- Pb-free lead plating;RoHS compliant
- Halogen-free according to IEC61249-2-21
- 100% UIS tested
- 100% ΔV_{ds} tested

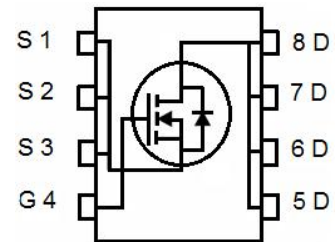
DFN 5X6-8L



Top View



Bottom View



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
A0130AG	NCEA0130AG	DFN5X6-8L	Ø330mm	12mm	5000units

Absolute Maximum Ratings ($T_C=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Limit	Unit
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Drain Current-Continuous	36	A
$I_D (100^\circ C)$	Drain Current-Continuous($T_C=100^\circ C$)	21	A
I_{DM}	Pulsed Drain Current	144	A
P_D	Maximum Power Dissipation	100	W
	Derating factor	0.68	W/ $^\circ C$
E_{AS}	Single pulse avalanche energy ^(Note 1)	164	mJ
T_J, T_{STG}	Operating Junction and Storage Temperature Range	-55 To 175	$^\circ C$

Thermal Characteristic

$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	1.5	$^{\circ}\text{C}/\text{W}$
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Electrical Characteristics ($T_c=25^{\circ}\text{C}$ unless otherwise noted)

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Off Characteristics						
B _V DSS	Drain-Source Breakdown Voltage	V _{GS} =0V I _D =250μA	100	-	-	V
I _D SS	Zero Gate Voltage Drain Current	V _{DS} =100V, V _{GS} =0V	-	-	1	μA
I _G SS	Gate-Body Leakage Current	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
On Characteristics						
V _{GS} (th)	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250μA	1.3	1.9	2.5	V
R _{DS} (ON)	Drain-Source On-State Resistance	V _{GS} =10V, I _D =15A	-	24	32	mΩ
		V _{GS} =4.5V, I _D =15A	-	27	35	
g _{FS}	Forward Transconductance	V _{DS} =5V, I _D =15A	-	15	-	S
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{DS} =50V, V _{GS} =0V, F=1.0MHz	-	2479	-	pF
C _{oss}	Output Capacitance		-	96	-	pF
C _{rss}	Reverse Transfer Capacitance		-	79	-	pF
Switching Characteristics <small>(Note 2)</small>						
t _d (on)	Turn-on Delay Time	V _{DD} =50V, R _L =3.3Ω V _{GS} =10V, R _{GEN} =3Ω	-	9	-	nS
t _r	Turn-on Rise Time		-	9	-	nS
t _d (off)	Turn-Off Delay Time		-	32	-	nS
t _f	Turn-Off Fall Time		-	8	-	nS
Q _g	Total Gate Charge	V _{DS} =50V, I _D =15A, V _{GS} =10V	-	67.2	-	nC
Q _{gs}	Gate-Source Charge		-	9.4	-	nC
Q _{gd}	Gate-Drain Charge		-	15.5	-	nC
Drain-Source Diode Characteristics						
V _{SD}	Diode Forward Voltage	V _{GS} =0V, I _S =15A	-	-	1.2	V
I _S	Diode Forward Current	-	-	-	36	A
t _{rr}	Reverse Recovery Time	T _J = 25°C, I _F = 15A di/dt = 100A/μs	-	32	-	nS
Q _{rr}	Reverse Recovery Charge		-	53	-	nC
t _{on}	Forward Turn-On Time	Intrinsic turn-on time is negligible (turn-on is dominated by LS+LD)				

Notes:

1. EAS condition : $T_J=25^{\circ}\text{C}, V_{DD}=50V, V_G=10V, L=0.5\text{mH}, R_g=25\Omega$.
2. Guaranteed by design, not subject to production.
3. These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_J(\text{MAX})=175^{\circ}\text{C}$. The SOA curve provides a single pulse rating.

Typical Electrical and Thermal Characteristics (Curves)

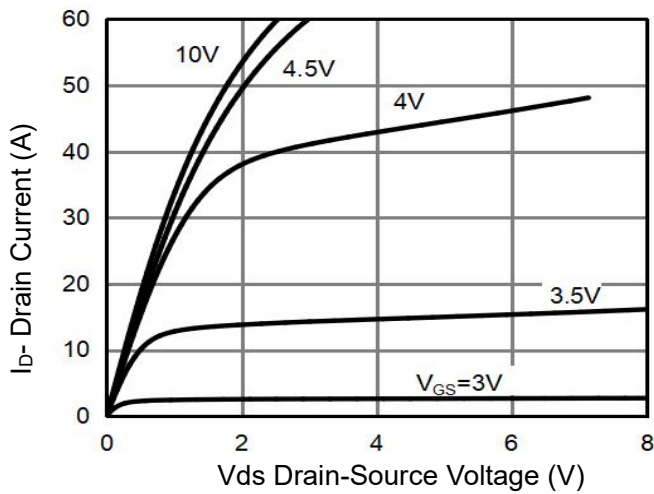


Figure 1 Output Characteristics

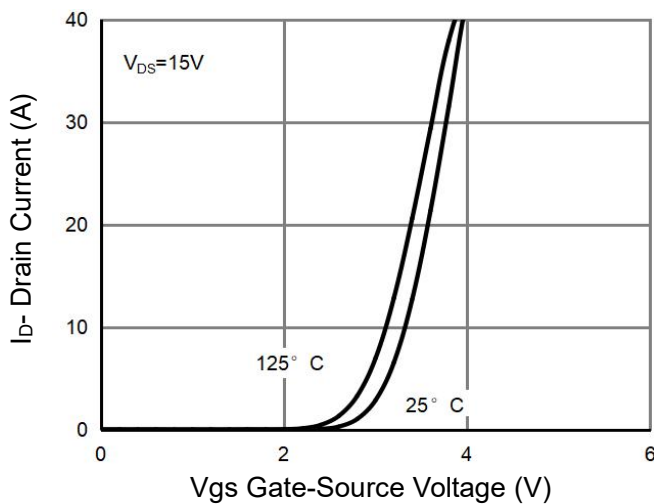


Figure 2 Transfer Characteristics

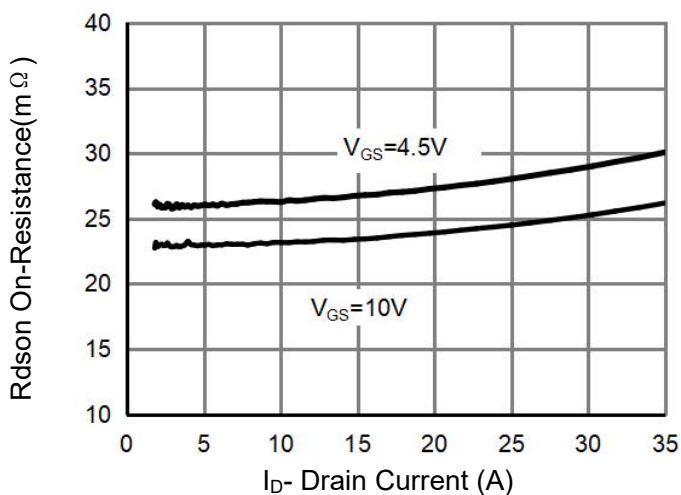


Figure 3 Rdson- Drain Current

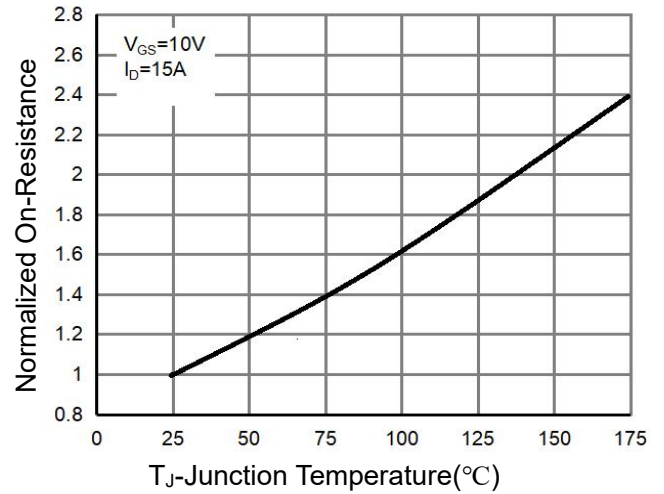


Figure 4 Rdson-Junction Temperature

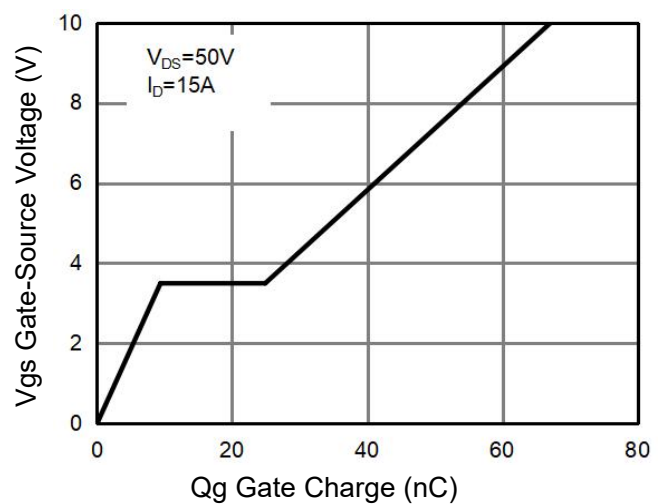


Figure 5 Gate Charge

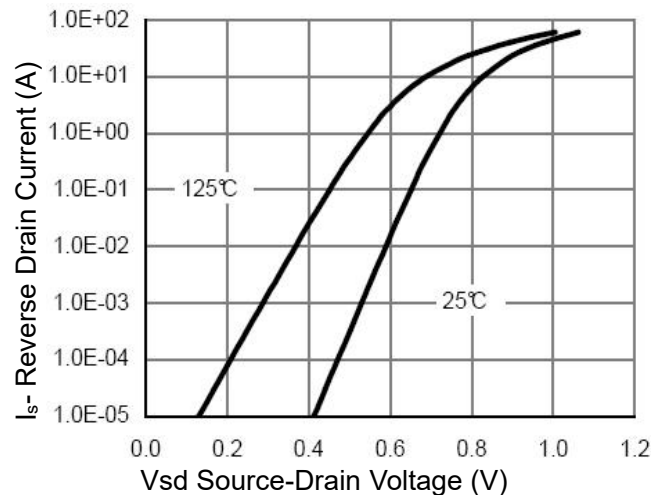


Figure 6 Source- Drain Diode Forward

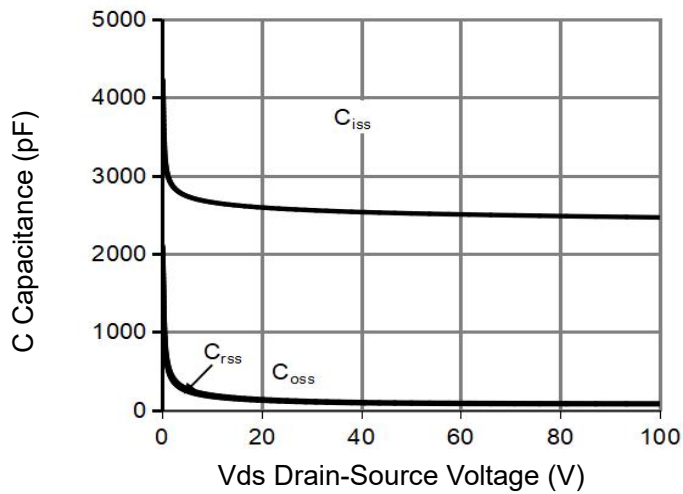


Figure 7 Capacitance vs Vds

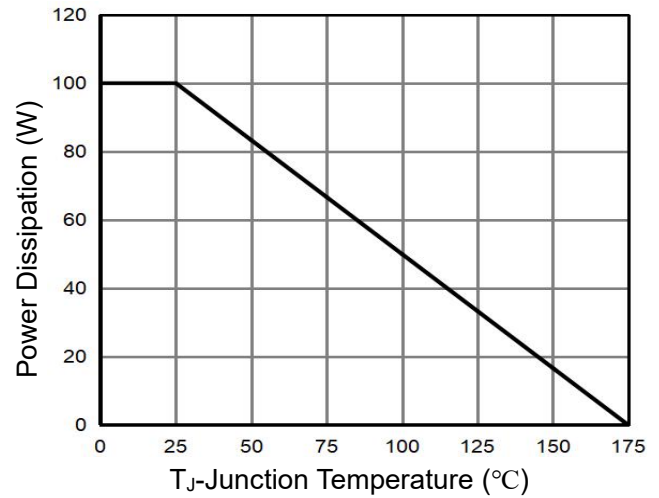


Figure 9 Power De-rating

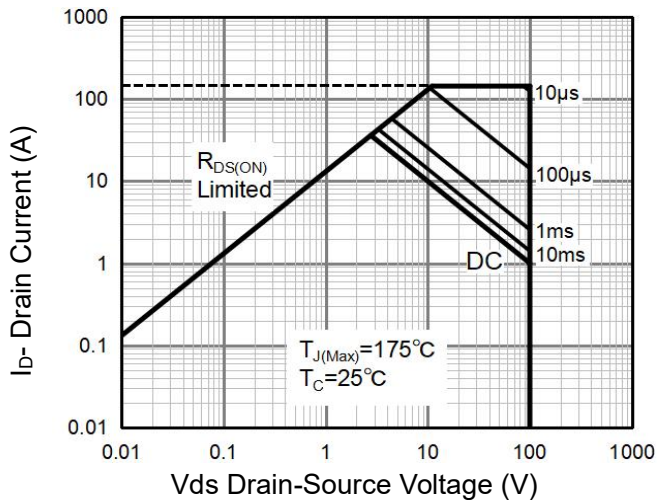


Figure 8 Safe Operation Area^(Note3)

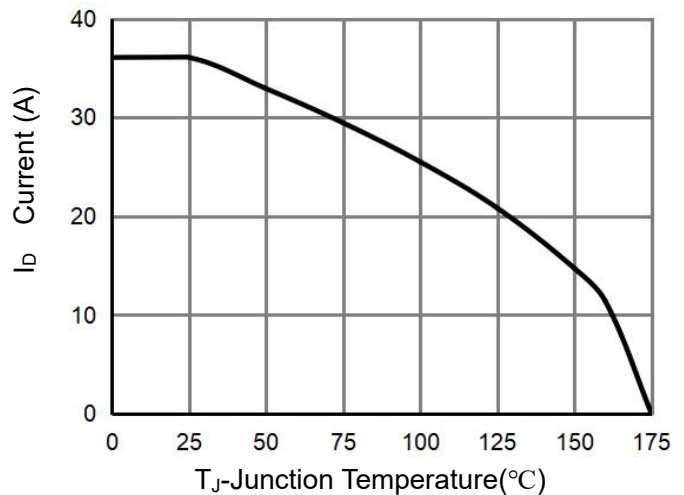


Figure 10 ID Current- Junction Temperature

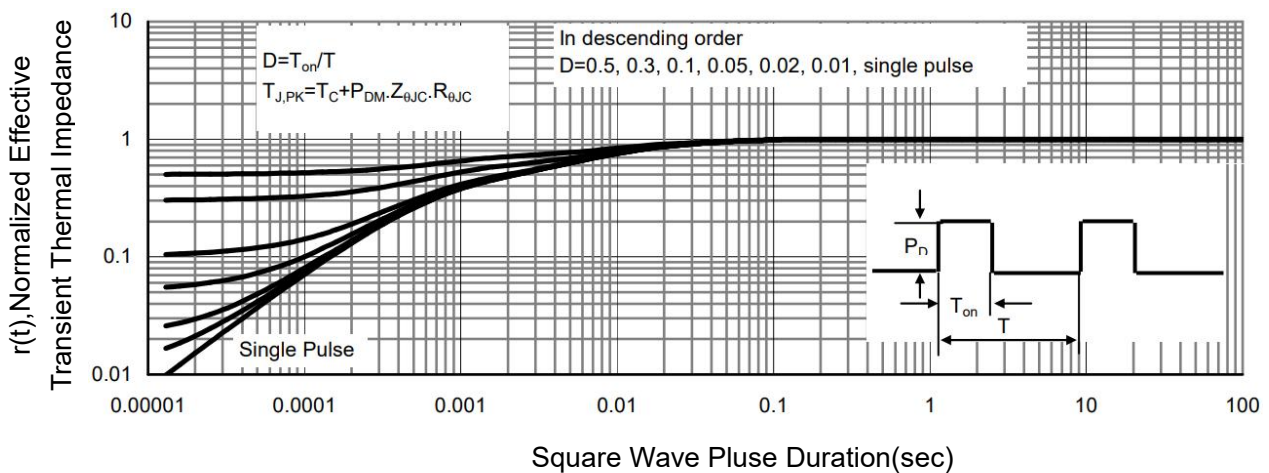
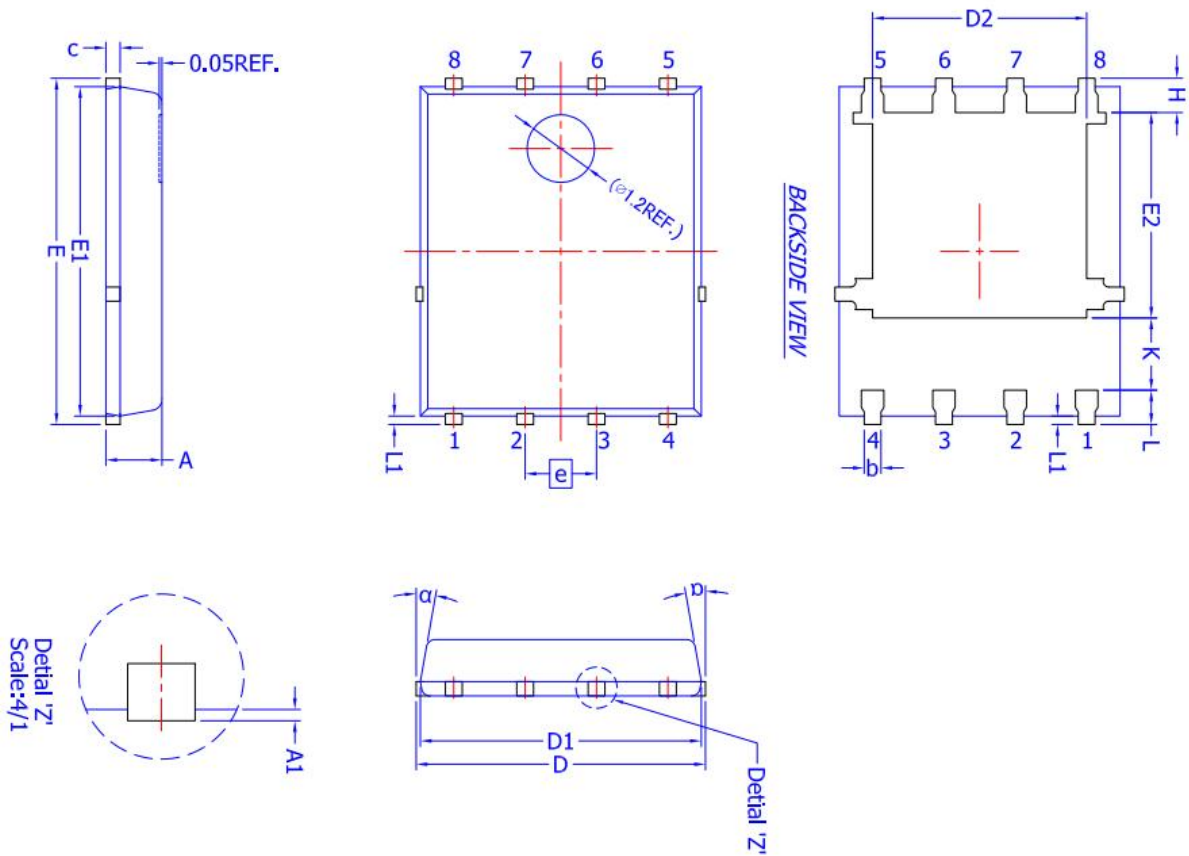


Figure 11 Normalized Maximum Transient Thermal Impedance

PDFN5X6-8L Package Information



DIM.	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.90	1.00	1.10
A1	0	-	0.05
b	0.30	0.40	0.50
c	0.20	0.25	0.30
D	5.15 BSC		
D1	5.00 BSC		
D2	3.76	3.81	3.86
E	6.15 BSC		
E1	5.80	5.85	5.90
E2	3.45	3.65	3.85
e	1.27 BSC		
H	0.51	0.61	0.71
K	1.10	-	-
L	0.51	0.61	0.71
L1	0.08	0.15	0.23
α	10°	11°	12°

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